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(54) **SUBSTRATE GLASS CORE PATTERNING FOR CTV IMPROVEMENT AND LAYER COUNT REDUCTION**

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(57) **ABSTRACT**

Embodiments disclosed herein include a package core. In an embodiment, the package core comprises a substrate with a first surface and a second surface opposite from the first surface. In an embodiment, the substrate comprise glass. In an embodiment, a via is provided through the substrate, where the via is electrically conductive. In an embodiment, a recess is formed into the first surface of the substrate, and a trace is embedded in the recess. In an embodiment, the trace is electrically conductive.